

Discription

The HCDSOD323-T05C protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.

Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Peak Power up to 30 Watts @ 8 x 20 _s Pulse
- ★ Low Leakage current
- ★ Response Time is Typically < 1 ns</p>
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ IEC61000-4-4 Level 4 EFT Protection

Orderingin formation







| Circuit | Diagram |
|---------|---------|
|---------|---------|

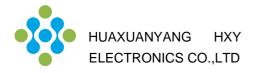
| Product ID | Pack | Qty(PCS) |
|----------------|---------|----------|
| HCDSOD323-T05C | SOD-323 | 3000 |

Absolute Ratings(Tamb = 25°C)

| Symbol | Parameter | Value | Units |
|------------------|---------------------------------------------------|-------------|-------|
| P _{PP} | Peak Pulse Power ($t_p = 8/20 \ \mu \ s$) | 30 | W |
| TL | Maximum lead temperature for soldering during 10s | 260 | °C |
| T _{stg} | Storage Temperature Range | -55 to +155 | °C |
| T _{op} | Operating Temperature Range | -40 to +125 | °C |
| Tj | Maximum junction temperature | 150 | °C |
| | IEC61000-4-2 (ESD) air discharge | ±10 | КV |
| | contact discharge | ±15 | |

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0*0.75*0.62 in.



| V _{RWM} (V) | I _R (uA) @V _{RWM} | V _{BR} (V)@ I _T (Note 1) | Ι _Τ | V _c (V) @ I _{PP} =1 A* | V _C (V) @ Max I _{PP} * | І _{РР} (А)* | Р _{РК} (W)* | C (pF) |
|-------------------------|------------------------------------------|-------------------------------------------------|----------------|-----------------------------------------------|-----------------------------------------------|-------------------------|-------------------------|-----------|
| Max | Max | Min | mA | Тур | Max | Мах | Мах | Мах |
| 5 | 1.0 | 5.4 | 1 | 9.5 | 12.9 | 2 | 30 | 2.5 |

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

*Surge current waveform per Figure 1.

1. V_{BR} is measured with a pluse test current I_T at an ambient temperature of $25\,^\circ\!\!\mathbb{C}$.

Typical Characteristics

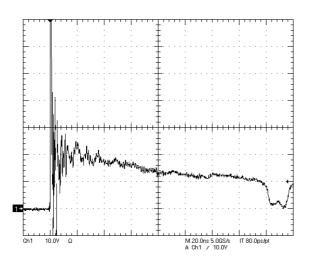


Figure 1. ESD Clamping Voltage Screenshot Positive 8 kV Contact per IEC61000-4-2

IEC 61000-4-2 Spec.

| Level | Test Voltage (kV) | First Peak Current (A) | Current at 30 ns (A) | Current at 60 ns (A) | |
|-------|-------------------------|------------------------------|-------------------------|-------------------------|--|
| 1 | 2 | 7.5 | 4 | 2 | |
| 2 | 4 | 15 | 8 | 4 | |
| 3 | 6 | 22.5 | 12 | 6 | |
| 4 | 8 | 30 | 16 | 8 | |

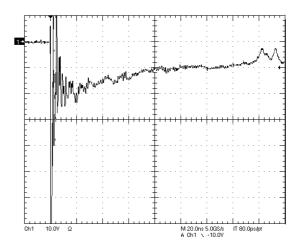


Figure 2. ESD Clamping Voltage Screenshot Negative 8 kV Contact per IEC61000-4-2

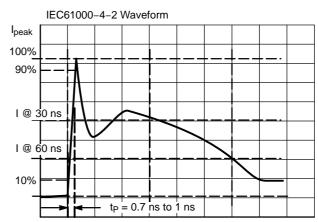


Figure 3. IEC61000-4-2 Spec



OUTLINE AND DIMENSIONS

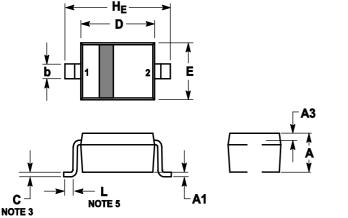
Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: MILLIMETERS.

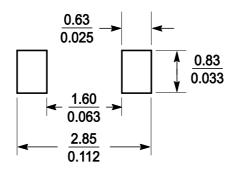
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



| | MILLIMETERS | | | S INCHES | | |
|----------------|-------------|------|-------|----------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| А | 0.8 | 0.9 | 1 | 0.031 | 0.035 | 0.04 |
| A1 | 0 | 0.05 | 0.1 | 0 | 0.002 | 0.004 |
| A3 | 0.15REF | | | 0.006REF | | |
| b | 0.25 | 0.32 | 0.4 | 0.01 | 0.012 | 0.016 |
| С | 0.089 | 0.12 | 0.177 | 0.003 | 0.005 | 0.007 |
| D | 1.6 | 1.7 | 1.8 | 0.062 | 0.066 | 0.07 |
| Е | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 |
| L | 0.08 | | | 0.003 | | |
| H _E | 2.3 | 2.5 | 2.7 | 0.09 | 0.098 | 0.105 |

SOLDERING FOOTPRINT





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